


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST25R3914-AQWT	UTIC*ST3914A	A	997G	2018-03-04
	Amount	UoM	Unit type	ST ECOPACK Grade
	70.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
able; if coating is used or other bulk	Matte tin	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	5x5x0.5mm	32	No lead	
Comment	Package : B04R VFQFPN 5X5X1 32L WETTABLE FLANKS DM00384332			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	UTIC*ST3914A				4999999.0	1000000.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.205	mg	supplier	die	Silicon (Si)	7440-21-3		5.865	mg	945205	83786
				supplier	metallization	Aluminium (Al)	7429-90-5		0.023	mg	3707	329
				supplier	metallization	Copper (Cu)	7440-50-8		0.115	mg	18533	1643
				supplier	metallization	Cobalt (Co)	7440-48-4		0.022	mg	3546	314
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	967	86
				supplier	metallization	Tungsten (W)	7440-33-7		0.013	mg	2095	186
				supplier	Passivation	Silicon Nitride	12033-89-5		0.015	mg	2417	214
				supplier	Passivation	Silicon Oxide	7631-86-9		0.146	mg	23529	2086
Leadframe-EFTEC64T	M-011 Other inorganic materials	20.121	mg	supplier	Alloy	Cu	7440-50-8		19.422	mg	972944	277455
					Alloy	Cr	7440-47-3		0.053	mg	2646	755
					Alloy	Sn	7440-31-5		0.049	mg	2450	699
					Alloy	Zn	7440-66-6		0.039	mg	1960	559
					Plating	Ag	7440-22-4		0.559	mg	20000	7979
					Bonding wire	Au	7440-57-5		0.482	mg	1000000	8695
Compound700LTD	M-011 Other inorganic materials	41.031	mg	supplier	Molding compound	Epoxy Resin	Trade secret		1.636	mg	50000	29485
					Molding compound	Phenol Resin	Trade secret		0.752	mg	23000	13563
					Molding compound	Silica (Amorphous)A	60676-86-0		36.124	mg	850000	487824
					Molding compound	Silica (Amorphous)B	7631-86-9		1.636	mg	50000	29485
					Molding compound	Metal Hydroxide	Trade secret		0.752	mg	23000	13563
					Molding compound	Carbon Black	1333-86-4		0.131	mg	4000	2359
Matte tin	M-011 Other inorganic materials	2.160	mg	supplier	Plating	Sn	7440-31-5		2.160	mg	1000000	38937